

General Description

The MY3422 is the high cell density trenched N-CH MOSFET, which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

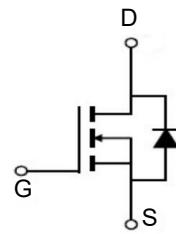
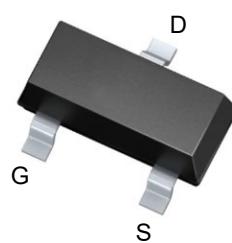


Features

V_{DSS}	60	V
I_D	3	A
$R_{DS(ON)}$ (at $V_{GS} = 10V$)	80	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	85	$m\Omega$

Application

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY3422	SOT-23	6003	3000

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	A
		$T_A = 100^\circ C$	A
I_{DM}	Pulsed Drain Current ^{note1}	12	A
P_D	Power Dissipation	$T_A = 25^\circ C$	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	83	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.4	2.0	V
R _{DS(on)} <small>note2</small>	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =3A	-	80	100	mΩ
		V _{GS} =4.5V, I _D =2A	-	85	120	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	350	-	pF
C _{oss}	Output Capacitance		-	29	-	pF
C _{rss}	Reverse Transfer Capacitance		-	23	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =3A, V _{GS} =10V	-	9	-	nC
Q _{gs}	Gate-Source Charge		-	1.5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =30V, I _D =2A, R _{GEN} =3Ω, V _{GS} =10V	-	5	-	ns
t _r	Turn-on Rise Time		-	7	-	ns
t _{d(off)}	Turn-off Delay Time		-	37	-	ns
t _f	Turn-off Fall Time		-	22	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	A	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	A	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S =3A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Electrical and Thermal Characteristics

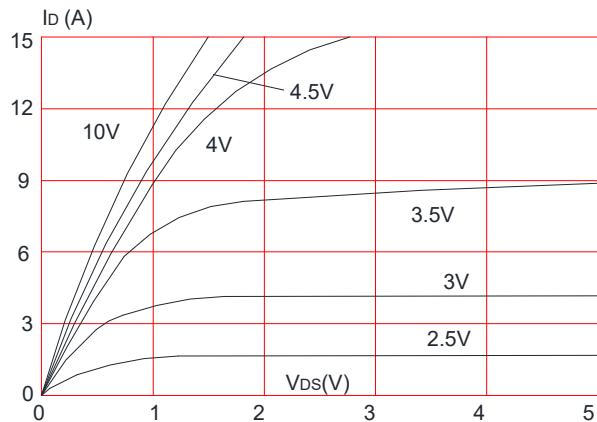
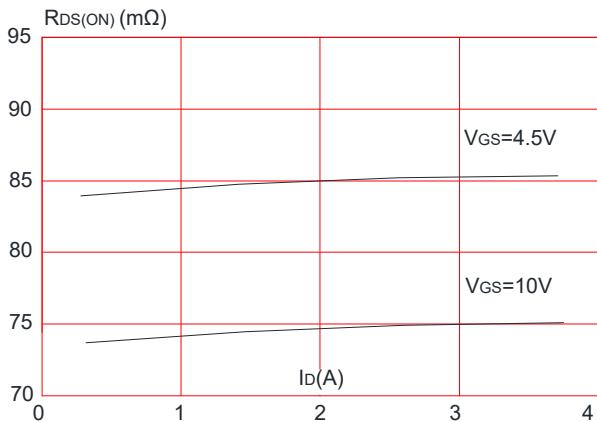
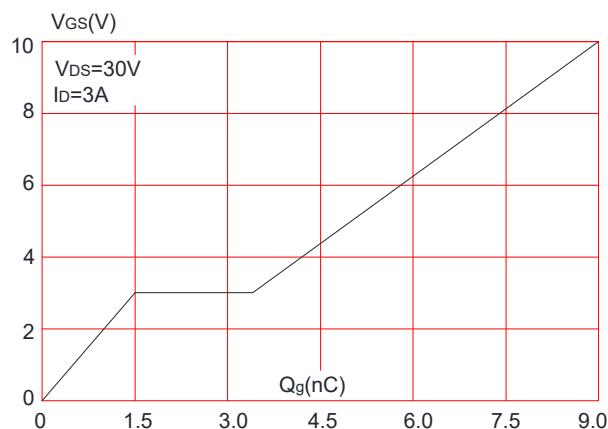
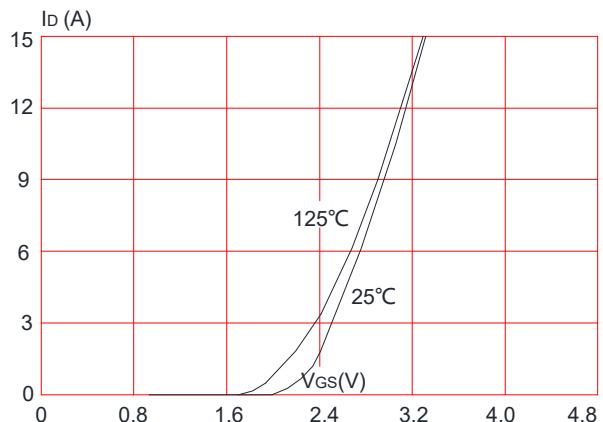
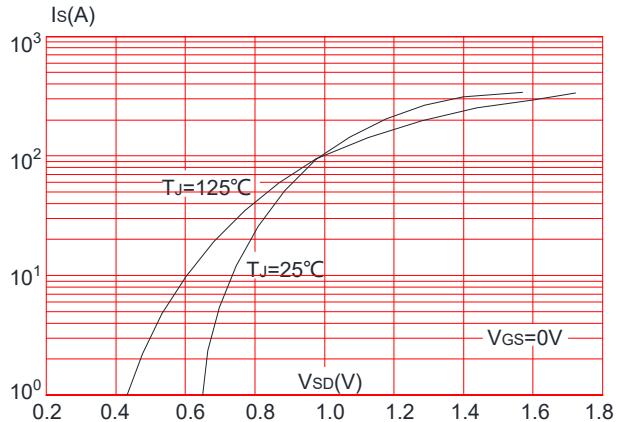
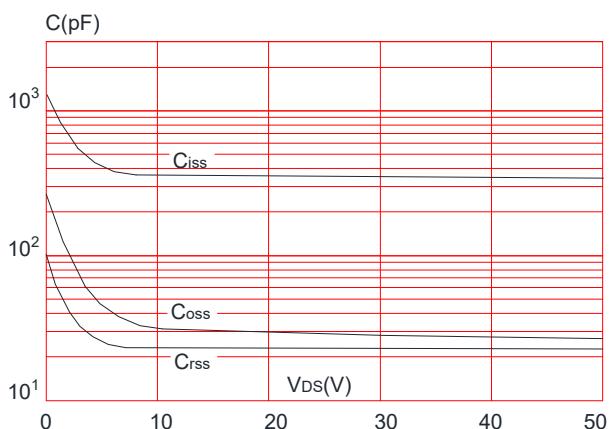
Figure 1: Output Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 5:** Gate Charge Characteristics**Figure 2:** Typical Transfer Characteristics**Figure 4:** Body Diode Characteristics**Figure 6:** Capacitance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

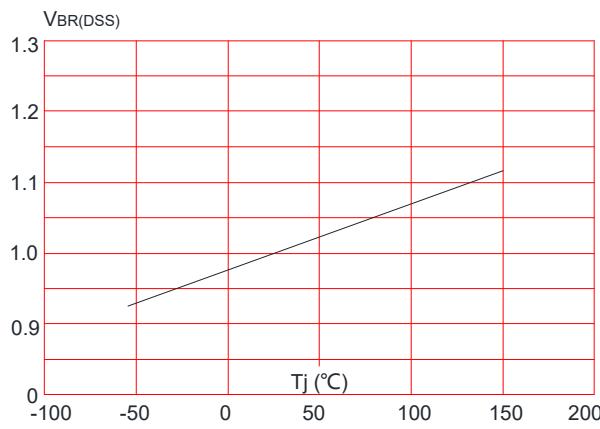


Figure 9: Maximum Safe Operating Area

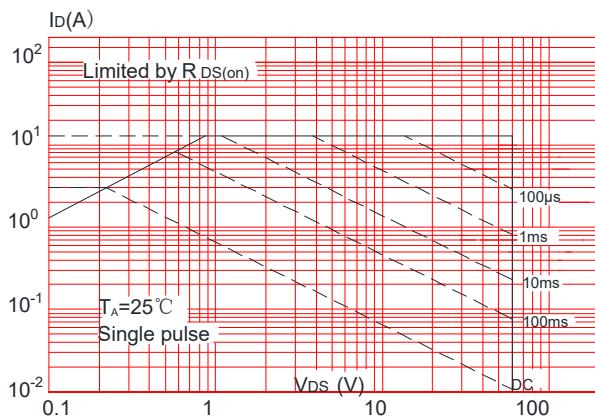


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

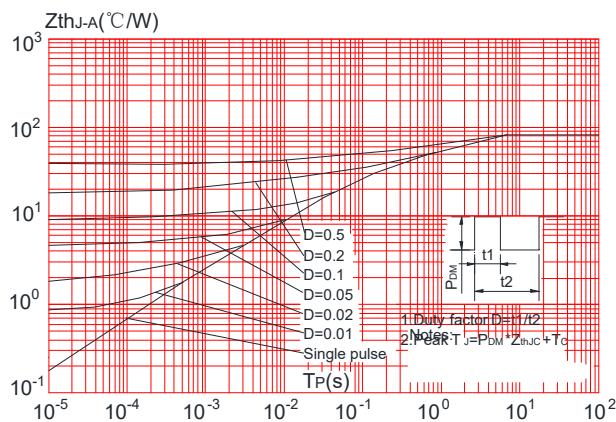


Figure 8: Normalized on Resistance vs. Junction Temperature

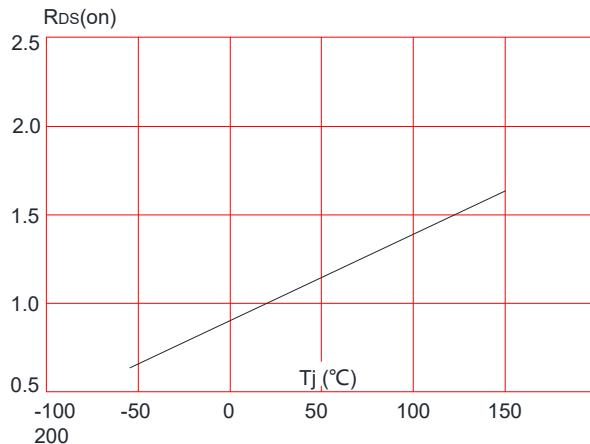
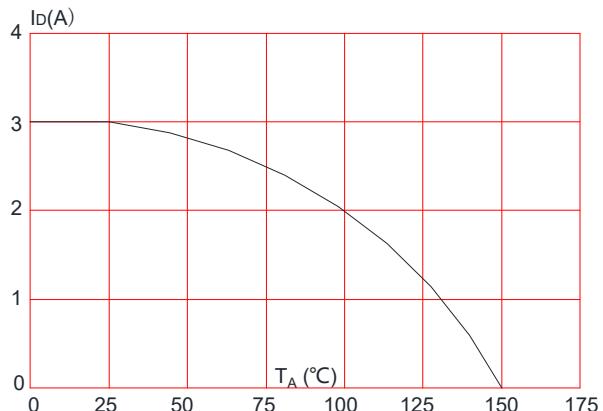
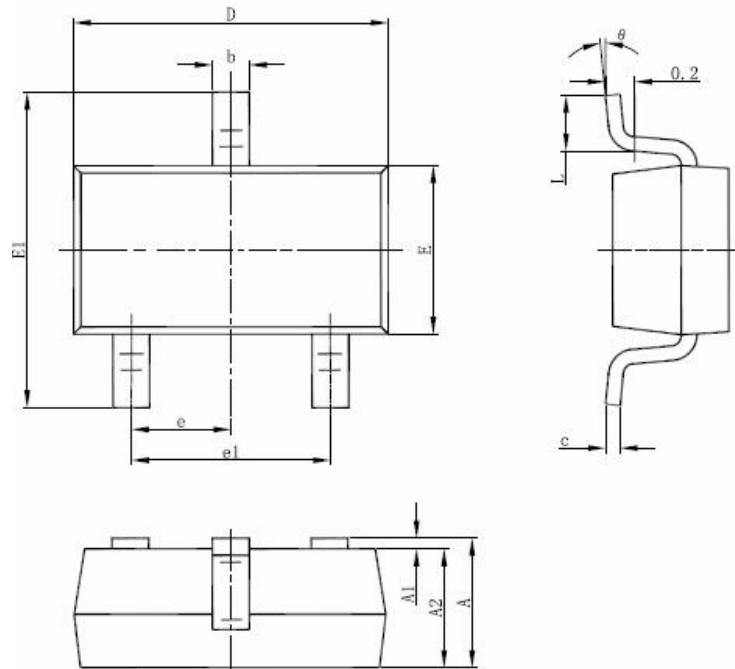


Figure 10: Maximum Continuous Drain Current vs.Ambient Temperature



Package Mechanical Data-SOT-23-3L


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°